FUTURE PLANS

We apply for the [**REDACTED**] as part of our efforts to foster our growth to the next stage and strengthen our competitive position in the chip customization service market. Specifically, we believe that the [**REDACTED**] will (i) promote our public profile and visibility in both domestic and international markets so that we may expand our customer base and promote our brand recognition, (ii) further broaden our access to international capital markets so that we may raise capital more efficiently both upon and after the [**REDACTED**] to support our growth, and (iii) attract talent and incentivize our employees. In addition, we choose [**REDACTED**] in Hong Kong because Hong Kong is a strategic gateway to international capital markets.

For a detailed description of our future plans, see "Business — Our Strategies."

USE OF [REDACTED]

We estimate that we will receive [**REDACTED**] from the [**REDACTED**] of HK$[**REDACTED**] million assuming no exercise of the [**REDACTED**], based on an assumed [**REDACTED**] of HK$[**REDACTED**] per Share, being the mid-point of the [**REDACTED**] of HK$[**REDACTED**] to HK$[**REDACTED**] per Share, after deducting [**REDACTED**] commissions and fees and other estimated [**REDACTED**] paid and payable by us in relation to the [**REDACTED**].

The following table sets forth a summary of the use of [**REDACTED**] from the [**REDACTED**] over the next five years. These plans are based on assumptions and are subject to uncertainties, including those set forth in "Risk Factors." As such, we cannot assure you that our plans will proceed as scheduled or that our goals will be fully achieved.

	2026 to 2027	2028 to 2029	2030 to 2031	Total from 2026 to 2031	Percentage of Total [REDACTED] from the [REDACTED]
	HK$	HK$	HK$	HK$	%
	(in millions, except percentages)				
Strengthening our core technology and research and development capabilities	[REDACTED]	[REDACTED]	[REDACTED]	[REDACTED]	[REDACTED]%
Strengthening collaboration with upstream and downstream partners	[REDACTED]	[REDACTED]	[REDACTED]	[REDACTED]	[REDACTED]%
Expanding our global footprint and strengthening international brand recognition	[REDACTED]	[REDACTED]	[REDACTED]	[REDACTED]	[REDACTED]%
Working capital and other general corporate purposes	[REDACTED]	[REDACTED]	[REDACTED]	[REDACTED]	[REDACTED]%
Total	[REDACTED]	[REDACTED]	[REDACTED]	[REDACTED]	**100.0%**

In line with our strategies, we plan to use the [**REDACTED**] from the [**REDACTED**] for the purposes and in the amounts set forth below:

- **approximately [REDACTED]% of the [REDACTED], or approximately HK$[REDACTED] million, will be used to strengthen our core technology and research and development capabilities, with a focus on developing and iterating the next-generation critical IPs to further secure our leading position in high-speed data interface IPs, high-speed memory interface IPs, and chiplet interconnect IPs — in particular,**

  - approximately [**REDACTED**]% of the [**REDACTED**], or approximately HK$[**REDACTED**] million, will be used to continue to develop the next-generation high-speed data interface IP through focusing on the research and development and silicon-proven validation of 112G long-reach SerDes and 224G long-reach SerDes to meet the high-bandwidth and low-latency requirements of massive AI model clusters that have a large number of interconnected accelerators, thereby achieving industry-leading performance metrics on advanced process nodes and strengthening our advantages in data center network interconnection. We are currently researching and developing 112G long-reach SerDes and plan to allocate resources to the research and development of 224G long-reach SerDes. We plan to retain existing talents and recruit new specialized IP SerDes design professionals, as well as a few front-end design, verification, and digital back-end design engineers. It is expected that a team of over [50] talents will be dedicated to this research and development initiative by 2031. The expected average annual salary of the professionals will range from RMB[**REDACTED**] million to RMB[**REDACTED**] million from 2026 to 2031. In addition, we will procure servers and other computing equipment to support this research and development initiative;

  - approximately [**REDACTED**]% of the [**REDACTED**], or approximately HK$[**REDACTED**] million, will be used to iterate the high-speed memory interface IP through (i) accelerating the mass-production validation of HBM3e controller and PHY IP and (ii) continuing the research and development for LPDDR6 and 3D DRAM controllers, thereby providing ultra-high bandwidth and low-latency memory solutions for trillion-parameter AI model training and meeting the rapid growth in AI computing demand over the next three to five years. We are currently conducting engineering validation of HBM3e controller and PHY IP. We also commenced research on LPDDR6 and 3D DRAM controllers and plan to continue to allocate resources towards their commercialization. We plan to retain existing talents and recruit new IP parallel interface design specialists, front-end design and verification engineers, and digital back-end design engineers. It is expected that a team of over [50] talents will be dedicated to this research and development initiative by 2031. The expected average annual salary of the professionals will range from RMB[**REDACTED**] million to RMB[**REDACTED**] million from 2026 to 2031. In addition, we will procure servers and other computing equipment to support this research and development initiative;

  - approximately [**REDACTED**]% of the [**REDACTED**], or approximately HK$[**REDACTED**] million, will be used to upgrade our chiplet heterogeneous integration platform through developing a standardized chiplet product matrix compatible with international mainstream standards such as UCIe by leveraging our participation in the development of national standards for chiplet interconnect technologies, thereby transitioning from customized design to a more modular assembly-based approach. We currently adopt standardized chiplet solutions based on international mainstream standards such as UCIe and have successfully implemented multiple projects. Starting 2027, we plan to allocate more resources to advance the development of proprietary chiplet-related IP. We will acquire appropriate IP in this field. In addition, we will retain existing talents and recruit new front-end design and verification engineers and back-end design professionals. It is expected that a team of around [30] talents will be dedicated to this research and development initiative by 2031. The expected average annual salary

of the professionals will range from RMB[**REDACTED**] million to RMB[**REDACTED**] million from 2026 to 2031. Furthermore, we will procure servers and other computing equipment to support the research and development initiative; and

- o approximately [**REDACTED**]% of the [**REDACTED**], or approximately HK$[**REDACTED**] million, will be used to enhance our capabilities in advanced process node adaptation and toolchain development through (i) continued investment in research and development for 3nm, 2nm, and more advanced nodes and (ii) further optimization of the intelligent toolchains within our automated IC technology platform, in order to improve our ability to adapt to leading-edge process technologies. Starting 2027, we plan to gradually allocate resources to design research at more advanced process nodes, including 3nm and 2nm. We plan to retain existing talents and recruit new high-end front-end design and verification engineers and a few digital back-end design engineers. It is expected that a team of over [30] talents will be dedicated to this research and development initiative by 2031. The expected average annual salary of the professionals will range from RMB[**REDACTED**] million to RMB[**REDACTED**] million from 2026 to 2031. In addition, we will procure servers and computing equipment to support the research and development initiative.

- **approximately [REDACTED]% of the [REDACTED], or approximately HK$[REDACTED] million, will be used to strengthen collaboration with upstream and downstream partners to establish a secure, controllable, and efficient closed-loop industry ecosystem — in particular,**

  - o approximately [**REDACTED**]% of the [**REDACTED**], or approximately HK$[**REDACTED**] million, will be used to further develop our process collaboration framework with semiconductor foundries, particularly the (i) early-stage research and development for leading global foundries on advanced nodes such as 3nm and 2nm to facilitate access to the latest process design kits, model libraries, and production capacity support and (ii) the development and validation of Foundation IPs for domestic mainstream foundries to support the application of domestic process technologies in high-end AI chips. We are the design solution partner of Samsung in China and are currently developing and validating Foundation IPs for advanced nodes for a leading domestic semiconductor foundry. In order to strengthen the collaboration with major domestic foundries at more advanced process nodes, we plan to acquire suitable IP in this field, develop analogue layout design, retain existing talents, and recruit new high-end front-end design, verification, and digital back-end design professionals. It is expected that a team of around [30] talents will be dedicated to this initiative by 2031. The expected average annual salary of the professionals will range from RMB[**REDACTED**] million to RMB[**REDACTED**] million from 2026 to 2031. In addition, we will procure servers and computing equipment to support this development strategy;

  - o approximately [**REDACTED**]% of the [**REDACTED**], or approximately HK$[**REDACTED**] million, will be used to strengthen our collaboration with advanced packaging providers and to maintain stable production capacity, through (i) the collaboration with domestic semiconductor assembly and test providers to develop co-design flows adapted for 2.5D/3D technologies and (ii) securing capacity on dedicated production lines to achieve yield ramp-up and reliable delivery for complex large-scale chips in high-density interconnect scenarios. We have accumulated extensive successful experience in 2.5D/3D technologies and have established close relationships with leading domestic packaging and testing enterprises. Going forward, we plan to strengthen our collaborations with these enterprises on more advanced process technologies. We will retain existing talents and recruit new high-end 2.5D/3D design professionals. It is expected that a team of around [20] talents will be dedicated to this initiative by 2031. The expected average annual salary of the professionals will range from RMB[**REDACTED**] million to RMB[**REDACTED**] million from 2026 to 2031. In addition, we may utilize part of the [**REDACTED**] to secure capacity on dedicated advanced packaging production lines and procure servers and computing equipment to support the initiative; and

- approximately [**REDACTED**]% of the [**REDACTED**], or approximately HK$[**REDACTED**] million, will be used to develop an AI hardware ecosystem that organically integrates technology platform and ecosystem partners, through connecting algorithm providers, system developers for specific application scenarios, and end users, to reduce the development barriers for high-performance AI ASICs and facilitate the commercialization and broader adoption of edge AI servers, interconnect chiplets, and memory components. We plan to retain our existing talents and recruit new high-end digital back-end design professionals. It is expected that a team of around [15] talents will be dedicated to this initiative by 2031. The expected average annual salary of the professionals will range from RMB[**REDACTED**] million to RMB[**REDACTED**] million from 2026 to 2031.

• **approximately [REDACTED]% of the [REDACTED], or approximately HK$[REDACTED] million, will be used to expand our global footprint and strengthen international brand recognition — in particular,**

  - approximately [**REDACTED**]% of the [**REDACTED**], or approximately HK$[**REDACTED**] million, will be used to establish global marketing and service networks through (i) establishing and expanding sales offices and technical support centers in major semiconductor hubs worldwide, such as Europe, Middle East, and the United States, (ii) building localized service teams in these areas, and (iii) renting office premises, aiming to enhance international market presence and penetration. It is expected that the new localized service teams will comprise up to [25] personnel with expected average annual salary ranging from RMB[**REDACTED**] million to RMB[**REDACTED**] million from 2026 to 2031;

  - approximately [**REDACTED**]% of the [**REDACTED**], or approximately HK$[**REDACTED**] million, will be used for branding and market promotion, through participating in top-tier international industry conferences and exhibitions, media outreach, and travel expenses of our sales and marketing personnel, to increase our visibility and enhance our brand recognition and industry presence as a leading chip customization service provider in China and globally; and

  - approximately [**REDACTED**]% of the [**REDACTED**], or approximately HK$[**REDACTED**] million, will be used for strategic investment in and mergers and acquisitions of companies that specialize in IP research and development in the IC industry, to enhance our technological capabilities and expand our presence in more regional markets. For more details of our selection criteria for the potential targets, see "Business — Our Strategies."

• **approximately [REDACTED]% of the [REDACTED], or approximately HK$[REDACTED] million, will be used for working capital and other general corporate purposes**.

If the [**REDACTED**] is set at the high point or the low point of the [**REDACTED**], the [**REDACTED**] of the [**REDACTED**] will increase or decrease by HK$[**REDACTED**] million or HK$[**REDACTED**] million, respectively. Under such circumstances, we will increase or decrease the allocation of the [**REDACTED**] to the above purposes on a pro rata basis.

If the [**REDACTED**] is exercised in full, the additional [**REDACTED**] of the [**REDACTED**] will be HK$[**REDACTED**] million, based on an assumed [**REDACTED**] of HK$[**REDACTED**] per Share, being the mid-point of the [**REDACTED**] of HK$[**REDACTED**] to HK$[**REDACTED**] per Share. Our Company may be required to [**REDACTED**] up to an aggregate of [**REDACTED**] additional Shares pursuant to the [**REDACTED**].

If the [**REDACTED**] of the [**REDACTED**] are insufficient to fund the foregoing purposes, we intend to finance the shortfall through a combination of cash generated from operating activities, bank borrowings, and other borrowings. To the extent that the [**REDACTED**] of the [**REDACTED**] are not immediately required for the above purposes, we will only hold such funds in short-term interest-bearing accounts at licensed commercial banks or other authorized financial institutions (as defined under the Securities and Futures Ordinance or other applicable laws and regulations in other jurisdictions). In such event, we will comply with the appropriate disclosure requirements under the Listing Rules.